

July 2007

## ES1F - ES1J

### **Fast Rectifiers**

### **Features**

- For surface mount applications.
- · Glass passivated junction.
- · Low profile package.
- · Easy pick and place.
- Built-in strain relief.
- · Superfast recovery times for high efficiency.



SMA(DO-214AC)
Color Band Denotes Cathode

## Absolute Maximum Ratings \* T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value				Units
		ES1F	ES1G	ES1H	ES1J	Units
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage	300 400 500 600		V		
I <sub>F(AV)</sub>	Average Rectified Forward Current	1.0		А		
I <sub>FSM</sub>	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave (JEDEC method)	30		А		
TJ	Junction Temperature	150		°C		
T <sub>STG</sub>	Storage Temperature Range	-55 to 150		°C		
P <sub>D</sub>	Power Dissipation	1.47		W		

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

### **Thermal Characteristics**

Symbol	Parameter	Value	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient *	85	°C/W
$R_{\theta JL}$	Thermal Resistance, Junction to Lead *	35	°C/W

<sup>\*</sup> P. C. B mounted on 0.2" x 0.2"( 5 x 5 mm) copper Pad Area.

### **Electrical Characteristics** $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Value		Units
V <sub>F</sub>	Maximum Forward Voltage @ I <sub>F</sub> = 1.0 A	1.3	1.7	V
T <sub>rr</sub>	Maximum Reverse Recovery Time IF = 0.5 A, IR = 1.0 A, IRR = 0.25 A	35		ns
I <sub>R</sub>	Maximum Reverse Current @ rated $V_R$ $T_A = 25^{\circ}C$ $T_A = 100^{\circ}C$			uA
C <sub>j</sub>	Typical Junction Capacitance $V_R = 4.0 \text{ V}, f = 1.0 \text{ MHz}$	10.0	8.0	pF

## **Typical Performance Characteristics**

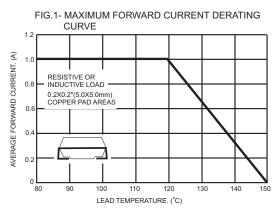


FIG.3- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

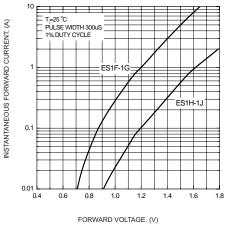


FIG.5- TYPICAL JUNCTION CAPACITANCE

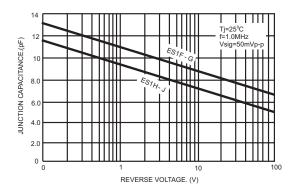


FIG.2- MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

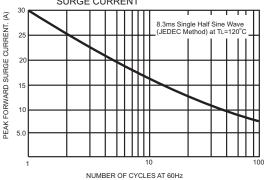
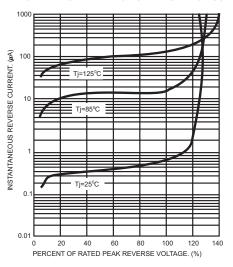
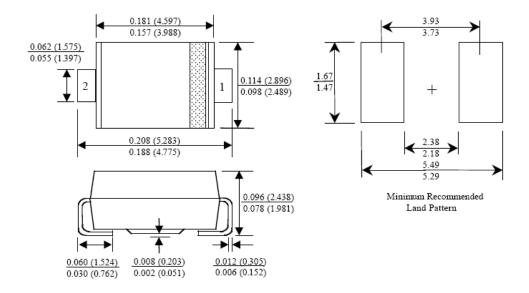


FIG.4-TYPICAL REVERSE CHARACTERISTICS



# **Package Dimensions**

## SMA / DO - 214AC



Dimensions in Millimeters





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